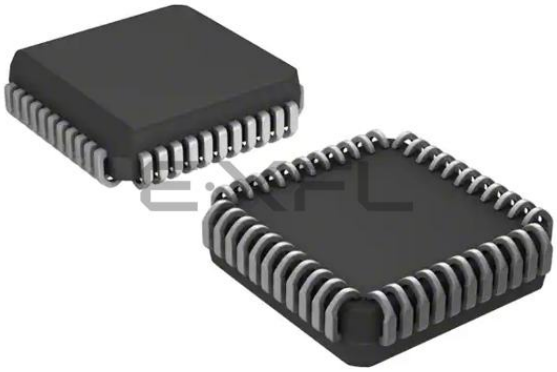

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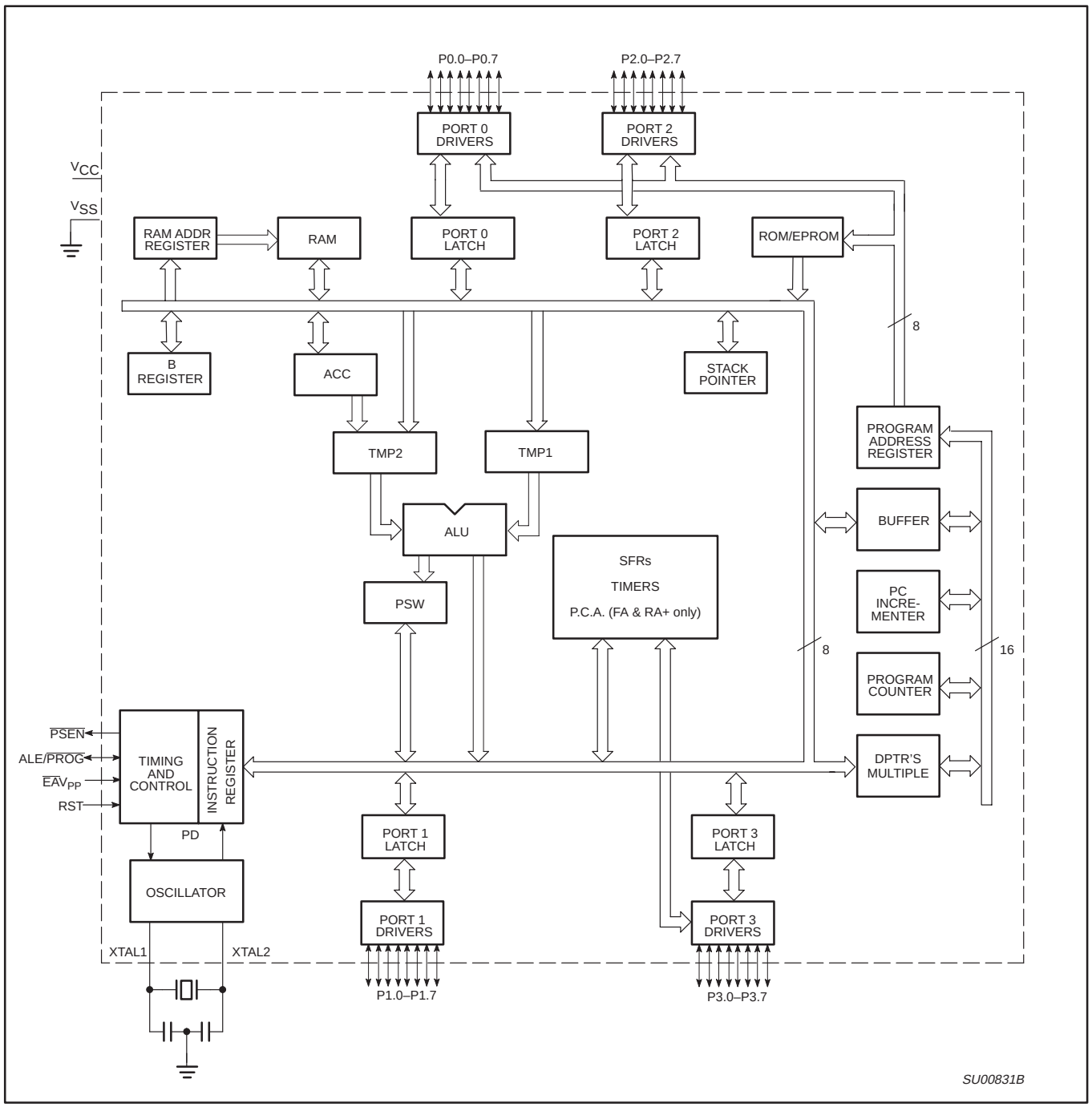
Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	8051
Core Size	8-Bit
Speed	16MHz
Connectivity	EBI/EMI, UART/USART
Peripherals	POR, PWM
Number of I/O	32
Program Memory Size	16KB (16K x 8)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	256 x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 5.5V
Data Converters	-
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-LCC (J-Lead)
Supplier Device Package	44-PLCC (16.59x16.59)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/p87c51fb-5a-512

BLOCK DIAGRAM



PIN DESCRIPTIONS

MNEMONIC	PIN NUMBER DIP	PIN NUMBER LCC	PIN NUMBER QFP	TYPE	NAME AND FUNCTION
V_{SS}	20	22	16	I	**Ground:** 0 V reference.
V_{CC}	40	44	38	I	**Power Supply:** This is the power supply voltage for normal, idle, and power-down operation.
P0.0–0.7	39–32	43–36	37–30	I/O	**Port 0:** Port 0 is an open-drain, bidirectional I/O port. Port 0 pins that have 1s written to them float and can be used as high-impedance inputs. Port 0 is also the multiplexed low-order address and data bus during accesses to external program and data memory. In this application, it uses strong internal pull-ups when emitting 1s. Port 0 also outputs the code bytes during program verification and received code bytes during EPROM programming. External pull-ups are required during program verification.
P1.0–P1.7	1–8	2–9	40–44, 1–3	I/O	**Port 1:** Port 1 is an 8-bit bidirectional I/O port with internal pull-ups. Port 1 pins that have 1s written to them are pulled high by the internal pull-ups and can be used as inputs. As inputs, port 1 pins that are externally pulled low will source current because of the internal pull-ups. (See DC Electrical Characteristics: I_{IL}). Port 1 also receives the low-order address byte during program memory verification.
					Alternate functions for 8XC51FX and 8XC51RX+ Port 1 include:
	1	2	40	I/O	**T2 (P1.0):** Timer/Counter 2 external count input/Clockout (see Programmable Clock-Out)
	2	3	41	I	**T2EX (P1.1):** Timer/Counter 2 Reload/Capture/Direction Control
	3	4	42	I	**ECI (P1.2):** External Clock Input to the PCA
	4	5	43	I/O	**CEX0 (P1.3):** Capture/Compare External I/O for PCA module 0
	5	6	44	I/O	**CEX1 (P1.4):** Capture/Compare External I/O for PCA module 1
	6	7	1	I/O	**CEX2 (P1.5):** Capture/Compare External I/O for PCA module 2
	7	8	2	I/O	**CEX3 (P1.6):** Capture/Compare External I/O for PCA module 3
	8	9	3	I/O	**CEX4 (P1.7):** Capture/Compare External I/O for PCA module 4
P2.0–P2.7	21–28	24–31	18–25	I/O	**Port 2:** Port 2 is an 8-bit bidirectional I/O port with internal pull-ups. Port 2 pins that have 1s written to them are pulled high by the internal pull-ups and can be used as inputs. As inputs, port 2 pins that are externally being pulled low will source current because of the internal pull-ups. (See DC Electrical Characteristics: I_{IL}). Port 2 emits the high-order address byte during fetches from external program memory and during accesses to external data memory that use 16-bit addresses (MOVX @DPTR). In this application, it uses strong internal pull-ups when emitting 1s. During accesses to external data memory that use 8-bit addresses (MOV @Ri), port 2 emits the contents of the P2 special function register. Some Port 2 pins receive the high order address bits during EPROM programming and verification.
P3.0–P3.7	10–17	11, 13–19	5, 7–13	I/O	**Port 3:** Port 3 is an 8-bit bidirectional I/O port with internal pull-ups. Port 3 pins that have 1s written to them are pulled high by the internal pull-ups and can be used as inputs. As inputs, port 3 pins that are externally being pulled low will source current because of the pull-ups. (See DC Electrical Characteristics: I_{IL}). Port 3 also serves the special features of the 80C51 family, as listed below:
	10	11	5	I	**RxD (P3.0):** Serial input port
	11	13	7	O	**TxD (P3.1):** Serial output port
	12	14	8	I	**$\overline{\text{INT0}}$ (P3.2):** External interrupt
	13	15	9	I	**$\overline{\text{INT1}}$ (P3.3):** External interrupt
	14	16	10	I	**T0 (P3.4):** Timer 0 external input
	15	17	11	I	**T1 (P3.5):** Timer 1 external input
	16	18	12	O	**$\overline{\text{WR}}$ (P3.6):** External data memory write strobe
	17	19	13	O	**$\overline{\text{RD}}$ (P3.7):** External data memory read strobe
RST	9	10	4	I	**Reset:** A high on this pin for two machine cycles while the oscillator is running, resets the device. An internal diffused resistor to V_{SS} permits a power-on reset using only an external capacitor to V_{CC}.
ALE/$\overline{\text{PROG}}$	30	33	27	O	**Address Latch Enable/Program Pulse:** Output pulse for latching the low byte of the address during an access to external memory. In normal operation, ALE is emitted at a constant rate of 1/6 the oscillator frequency, and can be used for external timing or clocking. Note that one ALE pulse is skipped during each access to external data memory. This pin is also the program pulse input ($\overline{\text{PROG}}$) during EPROM programming. ALE can be disabled by setting SFR auxiliary.0. With this bit set, ALE will be active only during a MOVX instruction.

8XC51FA/FB/FC AND 80C51FA ORDERING INFORMATION

	MEMORY SIZE 8K × 8	MEMORY SIZE 16K × 8	MEMORY SIZE 32K × 8	ROMless	TEMPERATURE RANGE °C AND PACKAGE	VOLTAGE RANGE	FREQ. (MHz)	DWG. #
ROM	P83C51FA–4N	P83C51FB–4N	P83C51FC–4N	P80C51FA–4N	0 to +70, 40-Pin Plastic Dual In-line Pkg.	2.7V to 5.5V	0 to 16	SOT129-1
OTP	P87C51FA–4N	P87C51FB–4N	P87C51FC–4N					
ROM	P83C51FA–4A	P83C51FB–4A	P83C51FC–4A	P80C51FA–4A	0 to +70, 44-Pin Plastic Leaded Chip Carrier	2.7V to 5.5V	0 to 16	SOT187-2
OTP	P87C51FA–4A	P87C51FB–4A	P87C51FC–4A					
ROM	P83C51FA–4B	P83C51FB–4B	P83C51FC–4B	P80C51FA–4B	0 to +70, 44-Pin Plastic Quad Flat Pack	2.7V to 5.5V	0 to 16	SOT307-2
OTP	P87C51FA–4B	P87C51FB–4B	P87C51FC–4B					
ROM	P83C51FA–5N	P83C51FB–5N	P83C51FC–5N	P80C51FA–5N	–40 to +85, 40-Pin Plastic Dual In-line Pkg.	2.7V to 5.5V	0 to 16	SOT129-1
OTP	P87C51FA–5N	P87C51FB–5N	P87C51FC–5N					
ROM	P83C51FA–5A	P83C51FB–5A	P83C51FC–5A	P80C51FA–5A	–40 to +85, 44-Pin Plastic Leaded Chip Carrier	2.7V to 5.5V	0 to 16	SOT187-2
OTP	P87C51FA–5A	P87C51FB–5A	P87C51FC–5A					
ROM	P83C51FA–5B	P83C51FB–5B	P83C51FC–5B	P80C51FA–5B	–40 to +85, 44-Pin Plastic Quad Flat Pack	2.7V to 5.5V	0 to 16	SOT307-2
OTP	P87C51FA–5B	P87C51FB–5B	P87C51FC–5B					
ROM	P83C51FA–IN	P83C51FB–IN	P83C51FC–IN	P80C51FA–IN	0 to +70, 40-Pin Plastic Dual In-line Pkg.	5V	0 to 33	SOT129-1
OTP	P87C51FA–IN	P87C51FB–IN	P87C51FC–IN					
ROM	P83C51FA–IA	P83C51FB–IA	P83C51FC–IA	P80C51FA–IA	0 to +70, 44-Pin Plastic Leaded Chip Carrier	5V	0 to 33	SOT187-2
OTP	P87C51FA–IA	P87C51FB–IA	P87C51FC–IA					
ROM	P83C51FA–IB	P83C51FB–IB	P83C51FC–IB	P80C51FA–IB	0 to +70, 44-Pin Plastic Quad Flat Pack	5V	0 to 33	SOT307-2
OTP	P87C51FA–IB	P87C51FB–IB	P87C51FC–IB					
ROM	P83C51FA–JN	P83C51FB–JN	P83C51FC–JN	P80C51FA–JN	–40 to +85, 40-Pin Plastic Dual In-line Pkg.	5V	0 to 33	SOT129-1
OTP	P87C51FA–JN	P87C51FB–JN	P87C51FC–JN					
ROM	P83C51FA–JA	P83C51FB–JA	P83C51FC–JA	P80C51FA–JA	–40 to +85, 44-Pin Plastic Leaded Chip Carrier	5V	0 to 33	SOT187-2
OTP	P87C51FA–JA	P87C51FB–JA	P87C51FC–JA					
ROM	P83C51FA–JB	P83C51FB–JB	P83C51FC–JB	P80C51FA–JB	–40 to +85, 44-Pin Plastic Quad Flat Pack	5V	0 to 33	SOT307-2
OTP	P87C51FA–JB	P87C51FB–JB	P87C51FC–JB					

Note: For Multi Time Programmable devices, See P89C51RX+ Flash datasheet.

Table 2. 8XC51FA/FB/FC, 8XC51RA+/RB+/RC+/RD+ Special Function Registers

SYMBOL	DESCRIPTION	DIRECT ADDRESS	BIT ADDRESS, SYMBOL, OR ALTERNATIVE PORT FUNCTION MSB							LSB	RESET VALUE
ACC*	Accumulator	E0H	E7	E6	E5	E4	E3	E2	E1	E0	00H
AUXR#	Auxiliary	8EH	–	–	–	–	–	–	EXTRAM (RX+ only)	AO	xxxxxx00B
AUXR1#	Auxiliary 1	A2H	–	–	–	LPEP[3]	GF3	0	–	DPS	xxx0xxx0B
B*	B register	F0H	F7	F6	F5	F4	F3	F2	F1	F0	00H
CCAP0H#	Module 0 Capture High	FAH									xxxxxxxxB
CCAP1H#	Module 1 Capture High	FBH									xxxxxxxxB
CCAP2H#	Module 2 Capture High	FCH									xxxxxxxxB
CCAP3H#	Module 3 Capture High	FDH									xxxxxxxxB
CCAP4H#	Module 4 Capture High	FEH									xxxxxxxxB
CCAP0L#	Module 0 Capture Low	EAH									xxxxxxxxB
CCAP1L#	Module 1 Capture Low	EBH									xxxxxxxxB
CCAP2L#	Module 2 Capture Low	ECH									xxxxxxxxB
CCAP3L#	Module 3 Capture Low	EDH									xxxxxxxxB
CCAP4L#	Module 4 Capture Low	EEH									xxxxxxxxB
CCAPM0#	Module 0 Mode	DAH	–	ECOM	CAPP	CAPN	MAT	TOG	PWM	ECCF	x0000000B
CCAPM1#	Module 1 Mode	DBH	–	ECOM	CAPP	CAPN	MAT	TOG	PWM	ECCF	x0000000B
CCAPM2#	Module 2 Mode	DCH	–	ECOM	CAPP	CAPN	MAT	TOG	PWM	ECCF	x0000000B
CCAPM3#	Module 3 Mode	DDH	–	ECOM	CAPP	CAPN	MAT	TOG	PWM	ECCF	x0000000B
CCAPM4#	Module 4 Mode	DEH	–	ECOM	CAPP	CAPN	MAT	TOG	PWM	ECCF	x0000000B
			DF	DE	DD	DC	DB	DA	D9	D8	
CCON*#	PCA Counter Control	D8H	CF	CR	–	CCF4	CCF3	CCF2	CCF1	CCF0	00x00000B
CH#	PCA Counter High	F9H									00H
CL#	PCA Counter Low	E9H									00H
CMOD#	PCA Counter Mode	D9H	CIDL	WDTE	–	–	–	CPS1	CPS0	ECF	00xxx000B
DPTR:	Data Pointer (2 bytes)										
DPH	Data Pointer High	83H									00H
DPL	Data Pointer Low	82H									00H
			AF	AE	AD	AC	AB	AA	A9	A8	
IE*	Interrupt Enable	A8H	EA	EC	ET2	ES	ET1	EX1	ET0	EX0	00H
			BF	BE	BD	BC	BB	BA	B9	B8	
IP*	Interrupt Priority	B8H	–	PPC	PT2	PS	PT1	PX1	PT0	PX0	x0000000B
			B7	B6	B5	B4	B3	B2	B1	B0	
IPH#	Interrupt Priority High	B7H	–	PPCH	PT2H	PSH	PT1H	PX1H	PT0H	PX0H	x0000000B
			87	86	85	84	83	82	81	80	
P0*	Port 0	80H	AD7	AD6	AD5	AD4	AD3	AD2	AD1	AD0	FFH
			97	96	95	94	93	92	91	90	
P1*	Port 1	90H	CEX4	CEX3	CEX2	CEX1	CEX0	ECI	T2EX	T2	FFH
			A7	A6	A5	A4	A3	A2	A1	A0	
P2*	Port 2	A0H	AD15	AD14	AD13	AD12	AD11	AD10	AD9	AD8	FFH
			B7	B6	B5	B4	B3	B2	B1	B0	
P3*	Port 3	B0H	$\overline{RD}$	$\overline{WR}$	T1	T0	$\overline{INT1}$	$\overline{INT0}$	TxD	RxD	FFH
PCON#[1]	Power Control	87H	SMOD1	SMOD0	–	POF[2]	GF1	GF0	PD	IDL	00xx0000B

* SFRs are bit addressable.
\# SFRs are modified from or added to the 80C51 SFRs.
– Reserved bits.
1. Reset value depends on reset source.
2. Bit will not be affected by Reset.
3. LPEP – Low Power OTP–EPROM only operation.

Table 2. 8XC51FA/FB/FC, 8XC51RA+/RB+/RC+/RD+ Special Function Registers (Continued)

SYMBOL	DESCRIPTION	DIRECT ADDRESS	BIT ADDRESS, SYMBOL, OR ALTERNATIVE PORT FUNCTION MSB							LSB	RESET VALUE
			D7	D6	D5	D4	D3	D2	D1	D0	
PSW*	Program Status Word	D0H	CY	AC	F0	RS1	RS0	OV	–	P	000000x0B
RACAP2H#	Timer 2 Capture High	CBH									00H
RACAP2L#	Timer 2 Capture Low	CAH									00H
SADDR#	Slave Address	A9H									00H
SADEN#	Slave Address Mask	B9H									00H
SBUF	Serial Data Buffer	99H									xxxxxxxxB
			9F	9E	9D	9C	9B	9A	99	98	
SCON*	Serial Control	98H	SM0/FE	SM1	SM2	REN	TB8	RB8	TI	RI	00H
SP	Stack Pointer	81H									07H
			8F	8E	8D	8C	8B	8A	89	88	
TCON*	Timer Control	88H	TF1	TR1	TF0	TR0	IE1	IT1	IE0	IT0	00H
			CF	CE	CD	CC	CB	CA	C9	C8	
T2CON*	Timer 2 Control	C8H	TF2	EXF2	RCLK	TCLK	EXEN2	TR2	C/$\overline{T2}$	CP/$\overline{RL2}$	00H
T2MOD#	Timer 2 Mode Control	C9H	–	–	–	–	–	–	T2OE	DCEN	xxxxxx00B
TH0	Timer High 0	8CH									00H
TH1	Timer High 1	8DH									00H
TH2#	Timer High 2	CDH									00H
TL0	Timer Low 0	8AH									00H
TL1	Timer Low 1	8BH									00H
TL2#	Timer Low 2	CCH									00H
TMOD	Timer Mode	89H	GATE	C/$\overline{T}$	M1	M0	GATE	C/$\overline{T}$	M1	M0	00H
WDTRST	HDW Watchdog Timer Reset (RX+ only)	0A6H									

* SFRs are bit addressable.
\# SFRs are modified from or added to the 80C51 SFRs.
– Reserved bits.

OSCILLATOR CHARACTERISTICS

XTAL1 and XTAL2 are the input and output, respectively, of an inverting amplifier. The pins can be configured for use as an on-chip oscillator.

To drive the device from an external clock source, XTAL1 should be driven while XTAL2 is left unconnected. There are no requirements on the duty cycle of the external clock signal, because the input to the internal clock circuitry is through a divide-by-two flip-flop. However, minimum and maximum high and low times specified in the data sheet must be observed.

RESET

A reset is accomplished by holding the RST pin high for at least two machine cycles (24 oscillator periods), while the oscillator is running. To insure a good power-on reset, the RST pin must be high long enough to allow the oscillator time to start up (normally a few milliseconds) plus two machine cycles. At power-on, the voltage on V_{CC} and RST must come up at the same time for a proper start-up. Ports 1, 2, and 3 will asynchronously be driven to their reset condition when a voltage above V_{IH1} (min.) is applied to RESET.

LOW POWER MODES

Stop Clock Mode

The static design enables the clock speed to be reduced down to 0 MHz (stopped). When the oscillator is stopped, the RAM and Special Function Registers retain their values. This mode allows step-by-step utilization and permits reduced system power consumption by lowering the clock frequency down to any value. For lowest power consumption the Power Down mode is suggested.

Idle Mode

In the idle mode (see Table 3), the CPU puts itself to sleep while all of the on-chip peripherals stay active. The instruction to invoke the idle mode is the last instruction executed in the normal operating mode before the idle mode is activated. The CPU contents, the on-chip RAM, and all of the special function registers remain intact during this mode. The idle mode can be terminated either by any enabled interrupt (at which time the process is picked up at the interrupt service routine and continued), or by a hardware reset which starts the processor in the same manner as a power-on reset.

Power-Down Mode

To save even more power, a Power Down mode (see Table 3) can be invoked by software. In this mode, the oscillator is stopped and the instruction that invoked Power Down is the last instruction executed. The on-chip RAM and Special Function Registers retain their values down to 2.0V and care must be taken to return V_{CC} to the minimum specified operating voltages before the Power Down Mode is terminated.

Either a hardware reset or external interrupt can be used to exit from Power Down. Reset redefines all the SFRs but does not change the on-chip RAM. An external interrupt allows both the SFRs and the on-chip RAM to retain their values.

To properly terminate Power Down the reset or external interrupt should not be executed before V_{CC} is restored to its normal operating level and must be held active long enough for the oscillator to restart and stabilize (normally less than 10ms).

With an external interrupt, INT0 and INT1 must be enabled and configured as level-sensitive. Holding the pin low restarts the oscillator but bringing the pin back high completes the exit. Once the interrupt is serviced, the next instruction to be executed after RETI will be the one following the instruction that put the device into Power Down.

LPEP

The LPEP bit (AUXR.4), only needs to be set for applications operating at V_{CC} less than 4V.

POWER OFF FLAG

The Power Off Flag (POF) is set by on-chip circuitry when the V_{CC} level on the 8XC51FX/8XC51RX+ rises from 0 to 5V. The POF bit can be set or cleared by software allowing a user to determine if the reset is the result of a power-on or a warm start after powerdown. The V_{CC} level must remain above 3V for the POF to remain unaffected by the V_{CC} level.

Design Consideration

- When the idle mode is terminated by a hardware reset, the device normally resumes program execution, from where it left off, up to two machine cycles before the internal reset algorithm takes control. On-chip hardware inhibits access to internal RAM in this event, but access to the port pins is not inhibited. To eliminate the possibility of an unexpected write when Idle is terminated by reset, the instruction following the one that invokes Idle should not be one that writes to a port pin or to external memory.

ONCE™ Mode

The ONCE ("On-Circuit Emulation") Mode facilitates testing and debugging of systems without the device having to be removed from the circuit. The ONCE Mode is invoked by:

1. Pull ALE low while the device is in reset and $\overline{PSEN}$ is high;
2. Hold ALE low as RST is deactivated.

While the device is in ONCE Mode, the Port 0 pins go into a float state, and the other port pins and ALE and $\overline{PSEN}$ are weakly pulled high. The oscillator circuit remains active. While the device is in this mode, an emulator or test CPU can be used to drive the circuit. Normal operation is restored when a normal reset is applied.

Programmable Clock-Out

A 50% duty cycle clock can be programmed to come out on P1.0. This pin, besides being a regular I/O pin, has two alternate functions. It can be programmed:

1. to input the external clock for Timer/Counter 2, or
2. to output a 50% duty cycle clock ranging from 61Hz to 4MHz at a 16MHz operating frequency.

To configure the Timer/Counter 2 as a clock generator, bit C/$\overline{T}$2 (in T2CON) must be cleared and bit T20E in T2MOD must be set. Bit TR2 (T2CON.2) also must be set to start the timer.

The Clock-Out frequency depends on the oscillator frequency and the reload value of Timer 2 capture registers (RCAP2H, RCAP2L) as shown in this equation:

$$\frac{\text{Oscillator Frequency}}{4 \times (65536 - \text{RCAP2H, RCAP2L})}$$

Where (RCAP2H,RCAP2L) = the content of RCAP2H and RCAP2L taken as a 16-bit unsigned integer.

In the Clock-Out mode Timer 2 roll-overs will not generate an interrupt. This is similar to when it is used as a baud-rate generator. It is possible to use Timer 2 as a baud-rate generator and a clock generator simultaneously. Note, however, that the baud-rate and the Clock-Out frequency will be the same.

Table 3. External Pin Status During Idle and Power-Down Mode

MODE	PROGRAM MEMORY	ALE	$\overline{PSEN}$	PORT 0	PORT 1	PORT 2	PORT 3
Idle	Internal	1	1	Data	Data	Data	Data
Idle	External	1	1	Float	Data	Address	Data
Power-down	Internal	0	0	Data	Data	Data	Data
Power-down	External	0	0	Float	Data	Data	Data

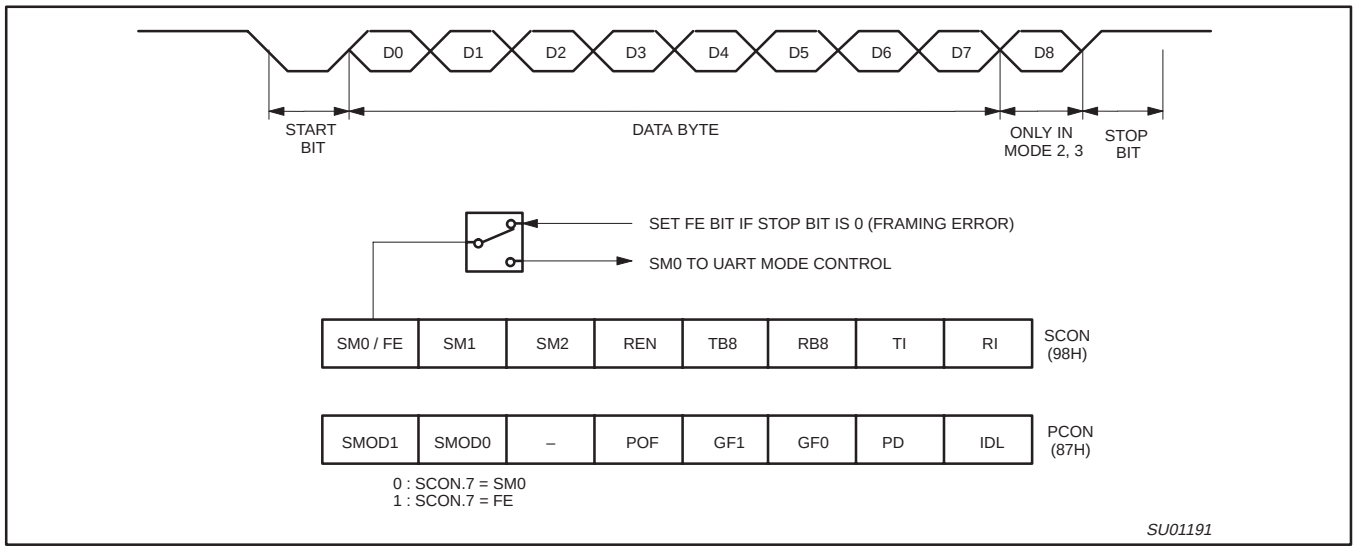


Figure 8. UART Framing Error Detection

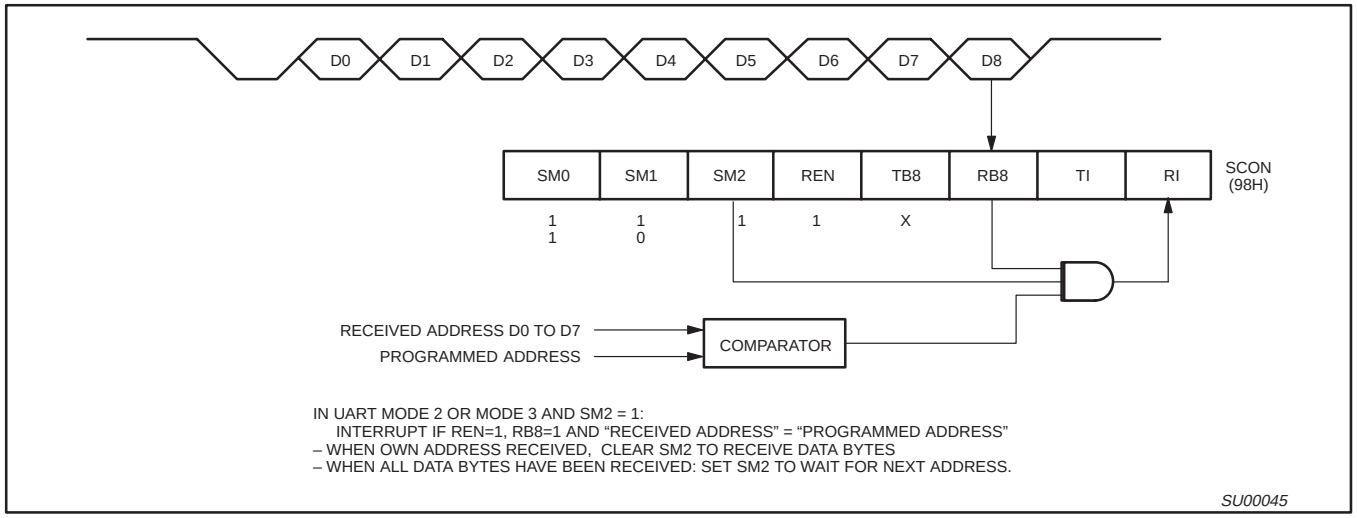


Figure 9. UART Multiprocessor Communication, Automatic Address Recognition

(8XC51FX and 8XC51RX+ ONLY)

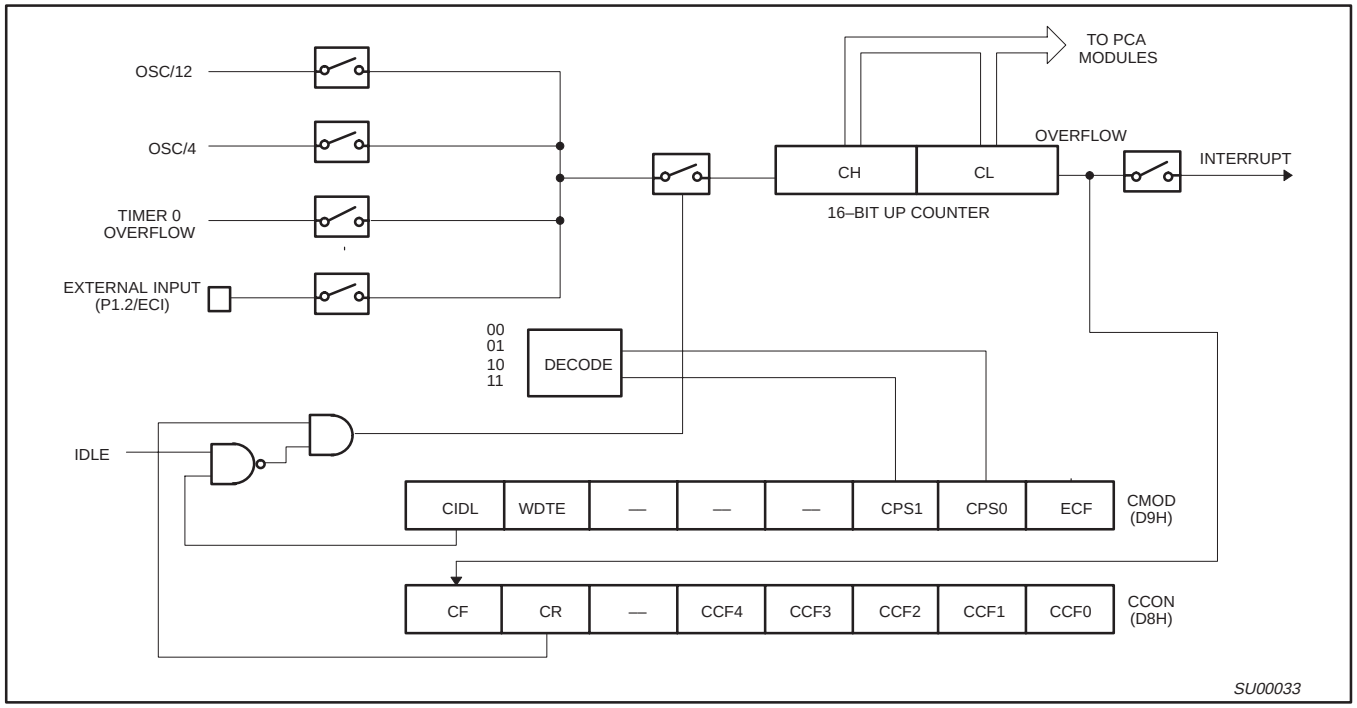


Figure 15. PCA Timer/Counter

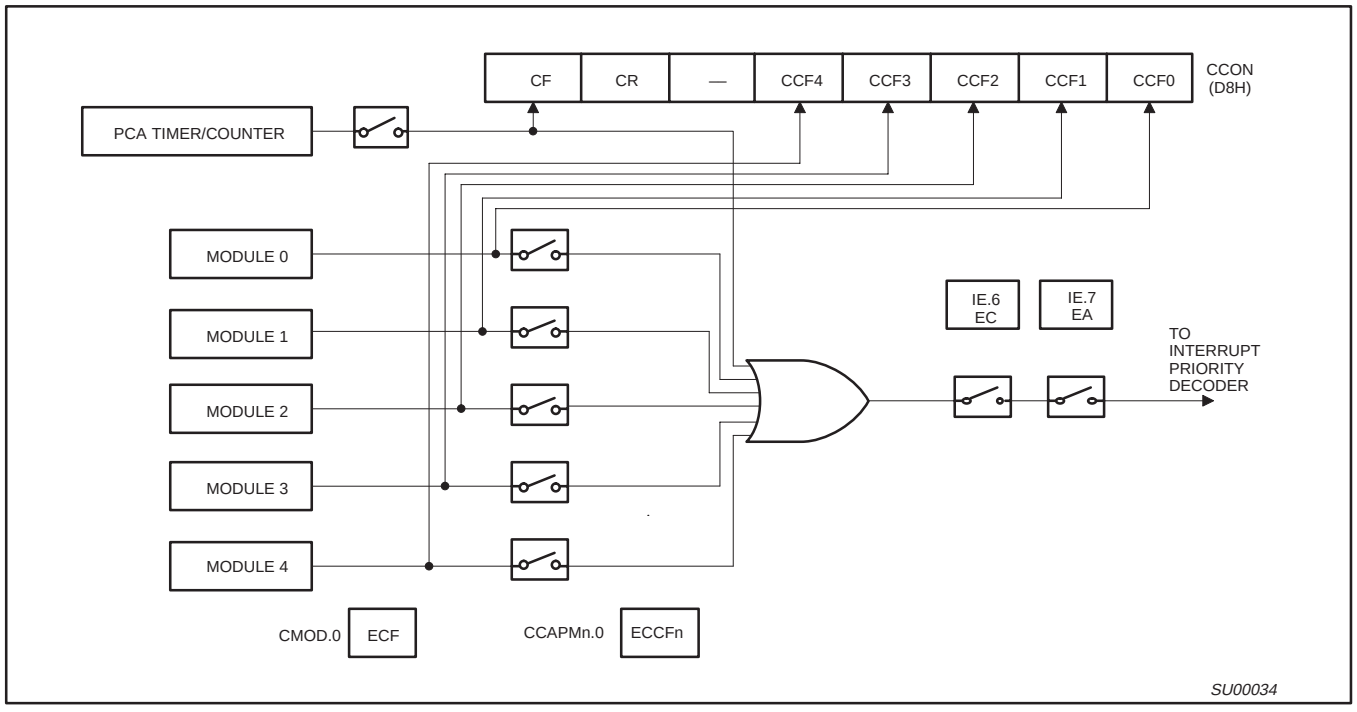


Figure 16. PCA Interrupt System

(8XC51FX and 8XC51RX+ ONLY)

CMOD Address = OD9H Reset Value = 00XX X000B

	CIDL	WDTE	–	–	–	CPS1	CPS0	ECF
Bit:	7	6	5	4	3	2	1	0

Symbol	Function
CIDL	Counter Idle control: CIDL = 0 programs the PCA Counter to continue functioning during idle Mode. CIDL = 1 programs it to be gated off during idle.
WDTE	Watchdog Timer Enable: WDTE = 0 disables Watchdog Timer function on PCA Module 4. WDTE = 1 enables it.
–	Not implemented, reserved for future use.*
CPS1	PCA Count Pulse Select bit 1.
CPS0	PCA Count Pulse Select bit 0.

CPS1	CPS0	Selected PCA Input**	
0	0	0	Internal clock, $f_{OSC} \div 12$
0	1	1	Internal clock, $f_{OSC} \div 4$
1	0	2	Timer 0 overflow
1	1	3	External clock at ECI/P1.2 pin (max. rate = $f_{OSC} \div 8$)

ECF	PCA Enable Counter Overflow interrupt: ECF = 1 enables CF bit in CCON to generate an interrupt. ECF = 0 disables that function of CF.

NOTE:
* User software should not write 1s to reserved bits. These bits may be used in future 8051 family products to invoke new features. In that case, the reset or inactive value of the new bit will be 0, and its active value will be 1. The value read from a reserved bit is indeterminate.
** f_{OSC} = oscillator frequency

SU00035

Figure 17. CMOD: PCA Counter Mode Register

CCON Address = OD8H Reset Value = 00X0 0000B

Bit Addressable

	CF	CR	–	CCF4	CCF3	CCF2	CCF1	CCF0
Bit:	7	6	5	4	3	2	1	0

Symbol	Function
CF	PCA Counter Overflow flag. Set by hardware when the counter rolls over. CF flags an interrupt if bit ECF in CMOD is set. CF may be set by either hardware or software but can only be cleared by software.
CR	PCA Counter Run control bit. Set by software to turn the PCA counter on. Must be cleared by software to turn the PCA counter off.
–	Not implemented, reserved for future use*.
CCF4	PCA Module 4 interrupt flag. Set by hardware when a match or capture occurs. Must be cleared by software.
CCF3	PCA Module 3 interrupt flag. Set by hardware when a match or capture occurs. Must be cleared by software.
CCF2	PCA Module 2 interrupt flag. Set by hardware when a match or capture occurs. Must be cleared by software.
CCF1	PCA Module 1 interrupt flag. Set by hardware when a match or capture occurs. Must be cleared by software.
CCF0	PCA Module 0 interrupt flag. Set by hardware when a match or capture occurs. Must be cleared by software.

NOTE:
* User software should not write 1s to reserved bits. These bits may be used in future 8051 family products to invoke new features. In that case, the reset or inactive value of the new bit will be 0, and its active value will be 1. The value read from a reserved bit is indeterminate.

SU00036

Figure 18. CCON: PCA Counter Control Register

(8XC51FX and 8XC51RX+ ONLY)

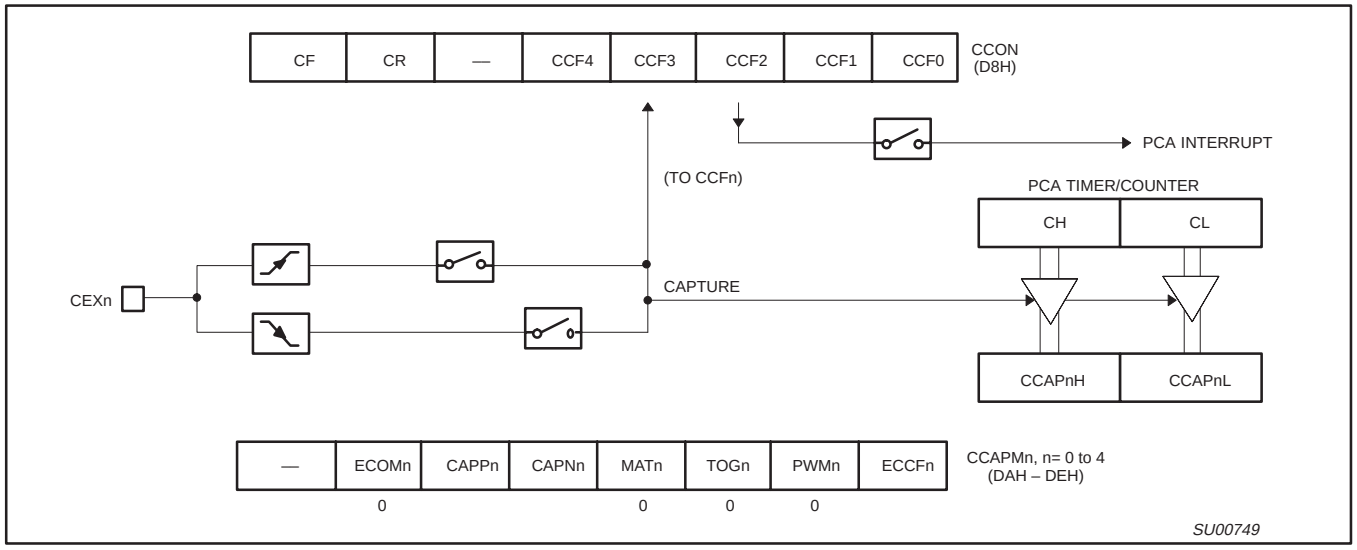


Figure 21. PCA Capture Mode

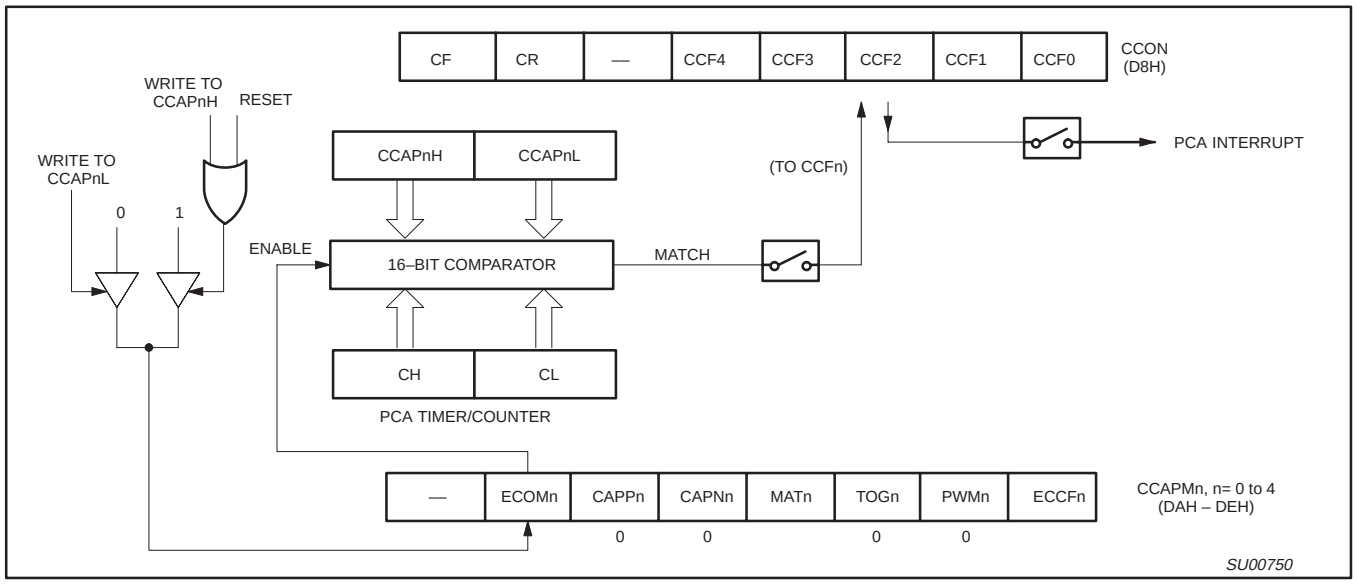


Figure 22. PCA Compare Mode

(8XC51FX and 8XC51RX+ ONLY)

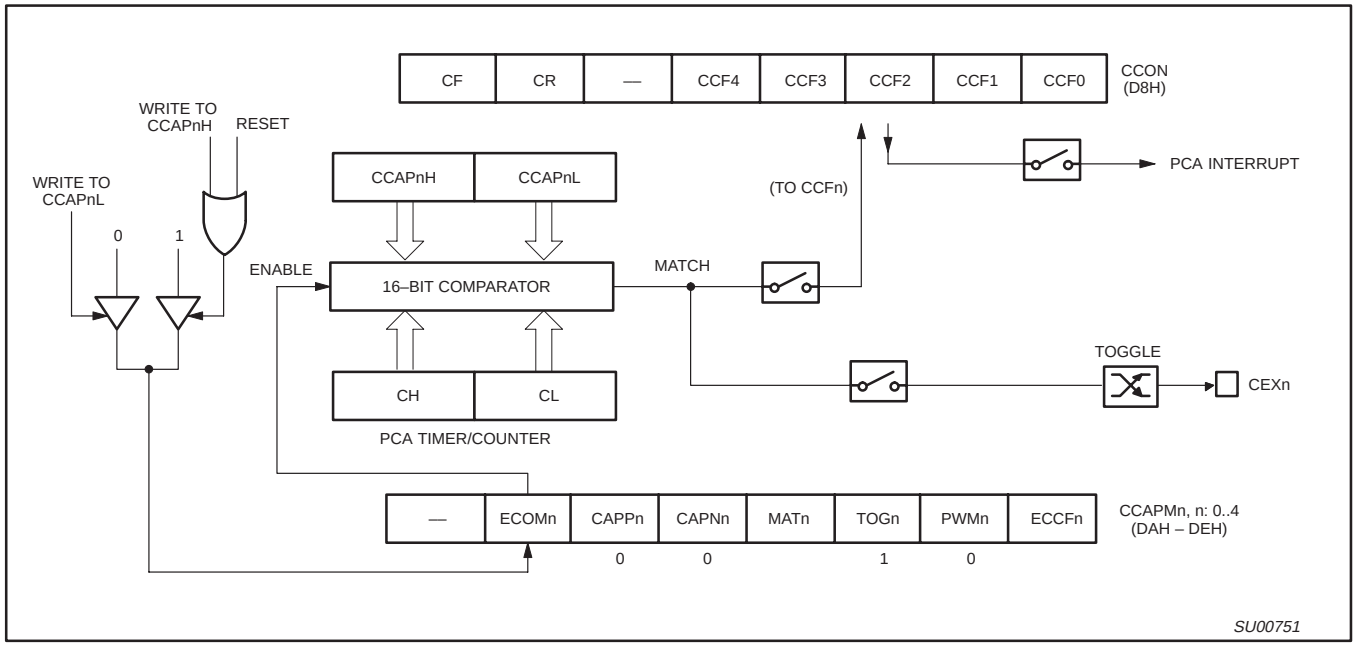


Figure 23. PCA High Speed Output Mode

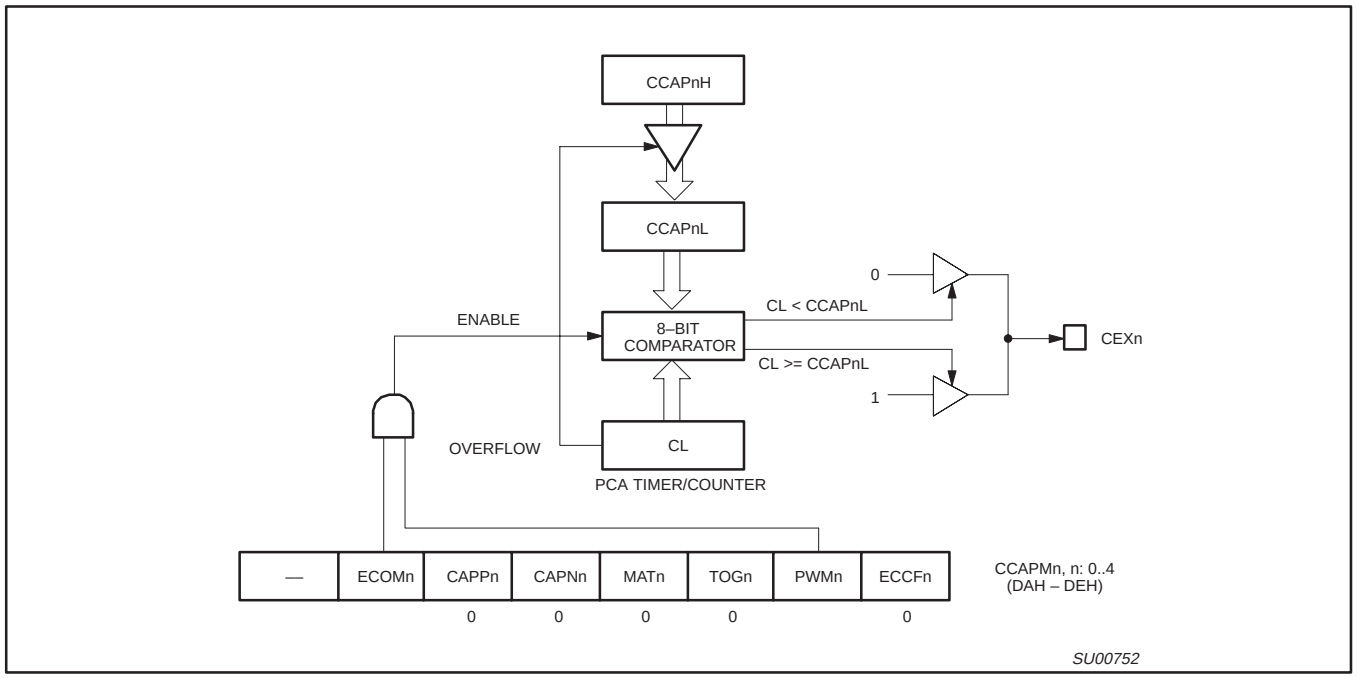


Figure 24. PCA PWM Mode

DC ELECTRICAL CHARACTERISTICS

T_{amb} = 0°C to +70°C or –40°C to +85°C, V_{CC} = 2.7V to 5.5V, V_{SS} = 0V (16MHz devices)

SYMBOL	PARAMETER	TEST CONDITIONS	LIMITS			UNIT
			MIN	TYP[1]	MAX	
V_{IL}	Input low voltage	4.0V < V_{CC} < 5.5V	–0.5		$0.2V_{CC}$–0.1	V
		2.7V<V_{CC}< 4.0V	–0.5		0.7	V
V_{IH}	Input high voltage (ports 0, 1, 2, 3, $\overline{EA}$)		$0.2V_{CC}$+0.9		V_{CC}+0.5	V
V_{IH1}	Input high voltage, XTAL1, RST		$0.7V_{CC}$		V_{CC}+0.5	V
V_{OL}	Output low voltage, ports 1, 2 [8]	V_{CC} = 2.7V I_{OL} = 1.6mA[2]			0.4	V
V_{OL1}	Output low voltage, port 0, ALE, $\overline{PSEN}$[8, 7]	V_{CC} = 2.7V I_{OL} = 3.2mA[2]			0.4	V
V_{OH}	Output high voltage, ports 1, 2, 3 [3]	V_{CC} = 2.7V I_{OH} = –20µA	V_{CC} – 0.7			V
		V_{CC} = 4.5V I_{OH} = –30µA	V_{CC} – 0.7			V
V_{OH1}	Output high voltage (port 0 in external bus mode), ALE[9], $\overline{PSEN}$[3]	V_{CC} = 2.7V I_{OH} = –3.2mA	V_{CC} – 0.7			V
I_{IL}	Logical 0 input current, ports 1, 2, 3	V_{IN} = 0.4V	–1		–50	µA
I_{TL}	Logical 1-to-0 transition current, ports 1, 2, 3[6]	V_{IN} = 2.0V See note 4			–650	µA
I_{LI}	Input leakage current, port 0	0.45 < V_{IN} < V_{CC} – 0.3			±10	µA
I_{CC}	Power supply current (see Figure 36):	See note 5				
	Active mode @ 16MHz (all except 8XC51RD+)				15	mA
	87C51RD+				16	mA
	Idle mode @ 16MHz				4	mA
	Power-down mode or clock stopped (see Figure 40 for conditions)	T_{amb} = 0°C to 70°C		3	50	µA
		T_{amb} = –40°C to +85°C			75	µA
R_{RST}	Internal reset pull-down resistor		40		225	kΩ
C_{IO}	Pin capacitance[10] (except $\overline{EA}$)				15	pF

NOTES:

1. Typical ratings are not guaranteed. The values listed are at room temperature, 5V.
2. Capacitive loading on ports 0 and 2 may cause spurious noise to be superimposed on the V_{OL}s of ALE and ports 1 and 3. The noise is due to external bus capacitance discharging into the port 0 and port 2 pins when these pins make 1-to-0 transitions during bus operations. In the worst cases (capacitive loading > 100pF), the noise pulse on the ALE pin may exceed 0.8V. In such cases, it may be desirable to qualify ALE with a Schmitt Trigger, or use an address latch with a Schmitt Trigger STROBE input. I_{OL} can exceed these conditions provided that no single output sinks more than 5mA and no more than two outputs exceed the test conditions.
3. Capacitive loading on ports 0 and 2 may cause the V_{OH} on ALE and $\overline{PSEN}$ to momentarily fall below the V_{CC}–0.7 specification when the address bits are stabilizing.
4. Pins of ports 1, 2 and 3 source a transition current when they are being externally driven from 1 to 0. The transition current reaches its maximum value when V_{IN} is approximately 2V.
5. See Figures 37 through 40 for I_{CC} test conditions, and Figure 36 for I_{CC} vs Freq.
   Active mode: I_{CC} = (0.9 × FREQ. + 1.1)mA for all devices except 8XC51RD+; 8XC51RD+ I_{CC} = (0.9 x Freq +2.1) mA
   Idle mode: I_{CC} = (0.18 × FREQ. +1.01)mA
6. This value applies to T_{amb} = 0°C to +70°C. For T_{amb} = –40°C to +85°C, I_{TL} = –750µA.
7. Load capacitance for port 0, ALE, and $\overline{PSEN}$ = 100pF, load capacitance for all other outputs = 80pF.
8. Under steady state (non-transient) conditions, I_{OL} must be externally limited as follows:
   Maximum I_{OL} per port pin: 15mA (*NOTE: This is 85°C specification.)
   Maximum I_{OL} per 8-bit port: 26mA
   Maximum total I_{OL} for all outputs: 71mA
   If I_{OL} exceeds the test condition, V_{OL} may exceed the related specification. Pins are not guaranteed to sink current greater than the listed test conditions.
9. ALE is tested to V_{OH1}, except when ALE is off then V_{OH} is the voltage specification.
10. Pin capacitance is characterized but not tested. Pin capacitance is less than 25pF. Pin capacitance of ceramic package is less than 15pF (except $\overline{EA}$ is 25pF).

DC ELECTRICAL CHARACTERISTICS

T_{amb} = 0°C to +70°C or –40°C to +85°C, 33MHz devices; 5V ±10%; V_{SS} = 0V

SYMBOL	PARAMETER	TEST CONDITIONS	LIMITS			UNIT
			MIN	TYP[1]	MAX	
V_{IL}	Input low voltage	4.5V < V_{CC} < 5.5V	–0.5		$0.2V_{CC}$–0.1	V
V_{IH}	Input high voltage (ports 0, 1, 2, 3, $\overline{EA}$)		$0.2V_{CC}$+0.9		V_{CC}+0.5	V
V_{IH1}	Input high voltage, XTAL1, RST		$0.7V_{CC}$		V_{CC}+0.5	V
V_{OL}	Output low voltage, ports 1, 2, 3 [8]	V_{CC} = 4.5V I_{OL} = 1.6mA[2]			0.4	V
V_{OL1}	Output low voltage, port 0, ALE, $\overline{PSEN}$ [7, 8]	V_{CC} = 4.5V I_{OL} = 3.2mA[2]			0.4	V
V_{OH}	Output high voltage, ports 1, 2, 3 [3]	V_{CC} = 4.5V I_{OH} = –30µA	V_{CC} – 0.7			V
V_{OH1}	Output high voltage (port 0 in external bus mode), ALE[9], $\overline{PSEN}$[3]	V_{CC} = 4.5V I_{OH} = –3.2mA	V_{CC} – 0.7			V
I_{IL}	Logical 0 input current, ports 1, 2, 3	V_{IN} = 0.4V	–1		–50	µA
I_{TL}	Logical 1-to-0 transition current, ports 1, 2, 3[6]	V_{IN} = 2.0V See note 4			–650	µA
I_{LI}	Input leakage current, port 0	0.45 < V_{IN} < V_{CC} – 0.3			±10	µA
I_{CC}	Power supply current (see Figure 36): Active mode (see Note 5) Idle mode (see Note 5) Power-down mode or clock stopped (see Figure 40 for conditions)	See note 5 T_{amb} = 0°C to 70°C T_{amb} = –40°C to +85°C		 3	 50 75	 µA µA
R_{RST}	Internal reset pull-down resistor		40		225	kΩ
C_{IO}	Pin capacitance[10] (except $\overline{EA}$)				15	pF

NOTES:

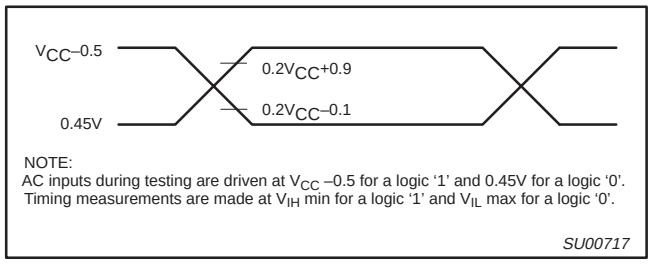
1. Typical ratings are not guaranteed. The values listed are at room temperature, 5V.
2. Capacitive loading on ports 0 and 2 may cause spurious noise to be superimposed on the V_{OL}s of ALE and ports 1 and 3. The noise is due to external bus capacitance discharging into the port 0 and port 2 pins when these pins make 1-to-0 transitions during bus operations. In the worst cases (capacitive loading > 100pF), the noise pulse on the ALE pin may exceed 0.8V. In such cases, it may be desirable to qualify ALE with a Schmitt Trigger, or use an address latch with a Schmitt Trigger STROBE input. I_{OL} can exceed these conditions provided that no single output sinks more than 5mA and no more than two outputs exceed the test conditions.
3. Capacitive loading on ports 0 and 2 may cause the V_{OH} on ALE and $\overline{PSEN}$ to momentarily fall below the V_{CC}–0.7 specification when the address bits are stabilizing.
4. Pins of ports 1, 2 and 3 source a transition current when they are being externally driven from 1 to 0. The transition current reaches its maximum value when V_{IN} is approximately 2V.
5. See Figures 37 through 40 for I_{CC} test conditions and Figure 36 for I_{CC} vs Freq.
   Active mode: $I_{CC(MAX)}$ = (0.9 × FREQ. + 1.1)mA. for all devices except 8XC51RD+; 8XC51RD+ I_{CC} = (0.9 x Freq +2.1) mA
   Idle mode: $I_{CC(MAX)}$ = (0.18 × FREQ. +1.0)mA
6. This value applies to T_{amb} = 0°C to +70°C. For T_{amb} = –40°C to +85°C, I_{TL} = –750µA.
7. Load capacitance for port 0, ALE, and $\overline{PSEN}$ = 100pF, load capacitance for all other outputs = 80pF.
8. Under steady state (non-transient) conditions, I_{OL} must be externally limited as follows:
   Maximum I_{OL} per port pin: 15mA (*NOTE: This is 85°C specification.)
   Maximum I_{OL} per 8-bit port: 26mA
   Maximum total I_{OL} for all outputs: 71mA
   If I_{OL} exceeds the test condition, V_{OL} may exceed the related specification. Pins are not guaranteed to sink current greater than the listed test conditions.
9. ALE is tested to V_{OH1}, except when ALE is off then V_{OH} is the voltage specification.
10. Pin capacitance is characterized but not tested. Pin capacitance is less than 25pF. Pin capacitance of ceramic package is less than 15pF (except $\overline{EA}$ is 25pF).

AC ELECTRICAL CHARACTERISTICS

T_{amb} = 0°C to +70°C or –40°C to +85°C, V_{CC} = +2.7V to +5.5V, V_{SS} = 0V[1, 2, 3]

SYMBOL	FIGURE	PARAMETER	16MHz CLOCK		VARIABLE CLOCK		UNIT
			MIN	MAX	MIN	MAX	
$1/t_{CLCL}$	29	Oscillator frequency[5] Speed versions : 4; 5;S			3.5	16	MHz
t_{LHLL}	29	ALE pulse width	85		$2t_{CLCL}$–40		ns
t_{AVLL}	29	Address valid to ALE low	22		t_{CLCL}–40		ns
t_{LLAX}	29	Address hold after ALE low	32		t_{CLCL}–30		ns
t_{LLIV}	29	ALE low to valid instruction in		150		$4t_{CLCL}$–100	ns
t_{LLPL}	29	ALE low to $\overline{PSEN}$ low	32		t_{CLCL}–30		ns
t_{PLPH}	29	$\overline{PSEN}$ pulse width	142		$3t_{CLCL}$–45		ns
t_{PLIV}	29	$\overline{PSEN}$ low to valid instruction in		82		$3t_{CLCL}$–105	ns
t_{PXIX}	29	Input instruction hold after $\overline{PSEN}$	0		0		ns
t_{PXIZ}	29	Input instruction float after $\overline{PSEN}$		37		t_{CLCL}–25	ns
t_{AVIV} [5]	29	Address to valid instruction in		207		$5t_{CLCL}$–105	ns
t_{PLAZ}	29	$\overline{PSEN}$ low to address float		10		10	ns
Data Memory							
t_{RLRH}	30, 31	$\overline{RD}$ pulse width	275		$6t_{CLCL}$–100		ns
t_{WLWH}	30, 31	$\overline{WR}$ pulse width	275		$6t_{CLCL}$–100		ns
t_{RLDV}	30, 31	$\overline{RD}$ low to valid data in		147		$5t_{CLCL}$–165	ns
t_{RHDX}	30, 31	Data hold after $\overline{RD}$	0		0		ns
t_{RHDZ}	30, 31	Data float after $\overline{RD}$		65		$2t_{CLCL}$–60	ns
t_{LLDV}	30, 31	ALE low to valid data in		350		$8t_{CLCL}$–150	ns
t_{AVDV}	30, 31	Address to valid data in		397		$9t_{CLCL}$–165	ns
t_{LLWL}	30, 31	ALE low to $\overline{RD}$ or $\overline{WR}$ low	137	239	$3t_{CLCL}$–50	$3t_{CLCL}$+50	ns
t_{AVWL}	30, 31	Address valid to $\overline{WR}$ low or $\overline{RD}$ low	122		$4t_{CLCL}$–130		ns
t_{QVWX}	30, 31	Data valid to $\overline{WR}$ transition	13		t_{CLCL}–50		ns
t_{WHQX}	30, 31	Data hold after $\overline{WR}$	13		t_{CLCL}–50		ns
t_{QVWH}	31	Data valid to $\overline{WR}$ high	287		$7t_{CLCL}$–150		ns
t_{RLAZ}	30, 31	$\overline{RD}$ low to address float		0		0	ns
t_{WHLH}	30, 31	$\overline{RD}$ or $\overline{WR}$ high to ALE high	23	103	t_{CLCL}–40	t_{CLCL}+40	ns
External Clock							
t_{CHCX}	33	High time	20		20	t_{CLCL}–t_{CLCX}	ns
t_{CLCX}	33	Low time	20		20	t_{CLCL}–t_{CHCX}	ns
t_{CLCH}	33	Rise time		20		20	ns
t_{CHCL}	33	Fall time		20		20	ns
Shift Register							
t_{XLXL}	32	Serial port clock cycle time	750		$12t_{CLCL}$		ns
t_{QVXH}	32	Output data setup to clock rising edge	492		$10t_{CLCL}$–133		ns
t_{XHQX}	32	Output data hold after clock rising edge	8		$2t_{CLCL}$–117		ns
t_{XHDX}	32	Input data hold after clock rising edge	0		0		ns
t_{XHDV}	32	Clock rising edge to input data valid		492		$10t_{CLCL}$–133	ns

NOTES:
1. Parameters are valid over operating temperature range unless otherwise specified.
2. Load capacitance for port 0, ALE, and $\overline{PSEN}$ = 100pF, load capacitance for all other outputs = 80pF.
3. Interfacing the microcontroller to devices with float times up to 45ns is permitted. This limited bus contention will not cause damage to Port 0 drivers.
4. See application note AN457 for external memory interface.
5. Parts are guaranteed to operate down to 0Hz.



NOTE:
AC inputs during testing are driven at V_{CC} –0.5 for a logic '1' and 0.45V for a logic '0'. Timing measurements are made at V_{IH} min for a logic '1' and V_{IL} max for a logic '0'.

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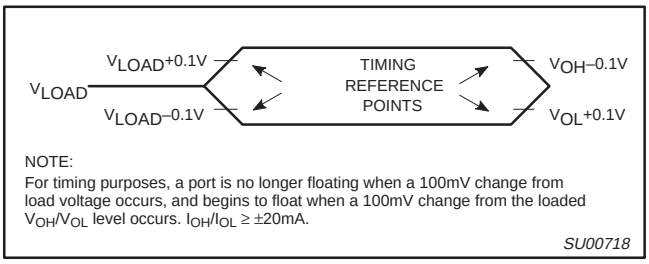
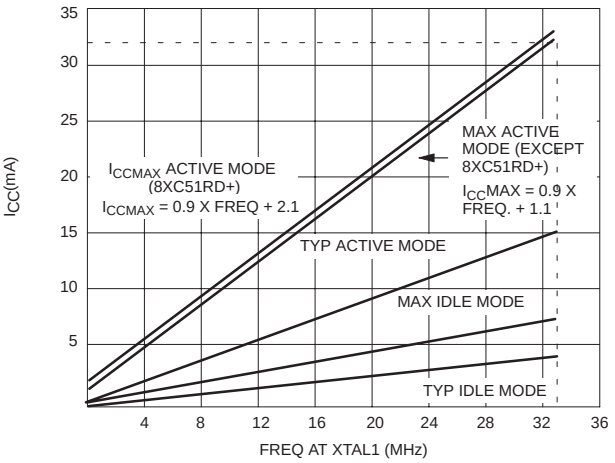
Figure 34. AC Testing Input/Output



NOTE:
For timing purposes, a port is no longer floating when a 100mV change from load voltage occurs, and begins to float when a 100mV change from the loaded V_{OH}/V_{OL} level occurs. $I_{OH}/I_{OL} \geq \pm 20$mA.

SU00718

Figure 35. Float Waveform



SU00837A

Figure 36. I_{CC} vs. FREQ
Valid only within frequency specifications of the device under test

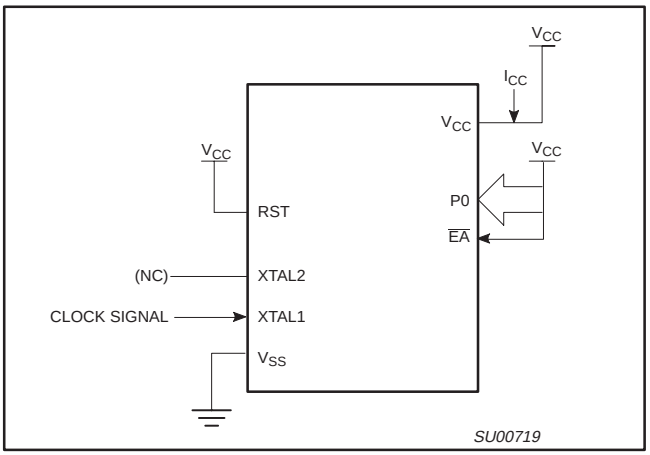


Figure 37. I_{CC} Test Condition, Active Mode
All other pins are disconnected

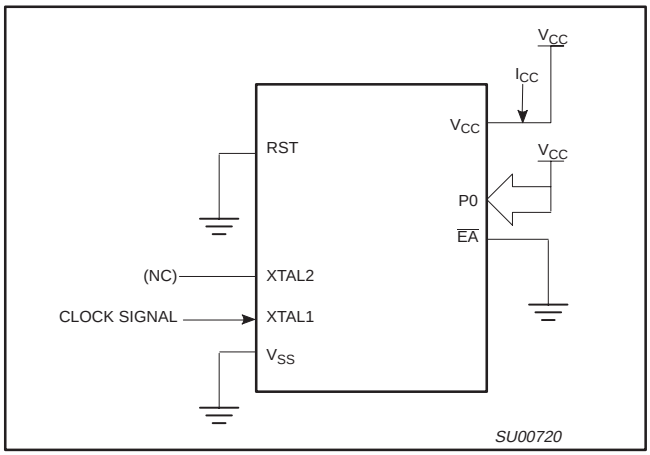


Figure 38. I_{CC} Test Condition, Idle Mode
All other pins are disconnected

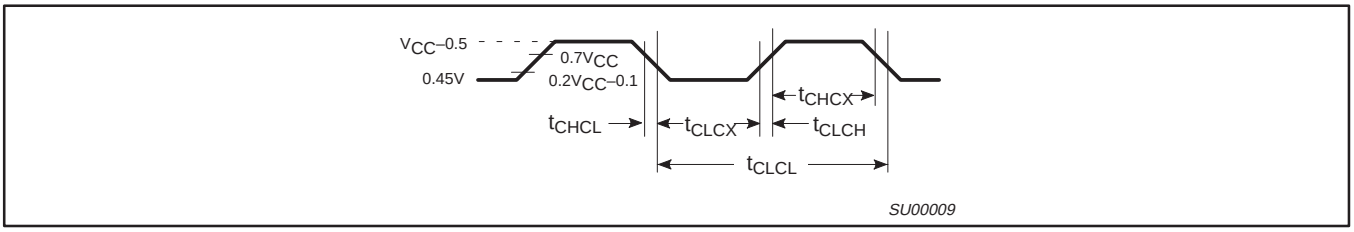


Figure 39. Clock Signal Waveform for I_{CC} Tests in Active and Idle Modes
$t_{CLCH} = t_{CHCL} = 5ns$

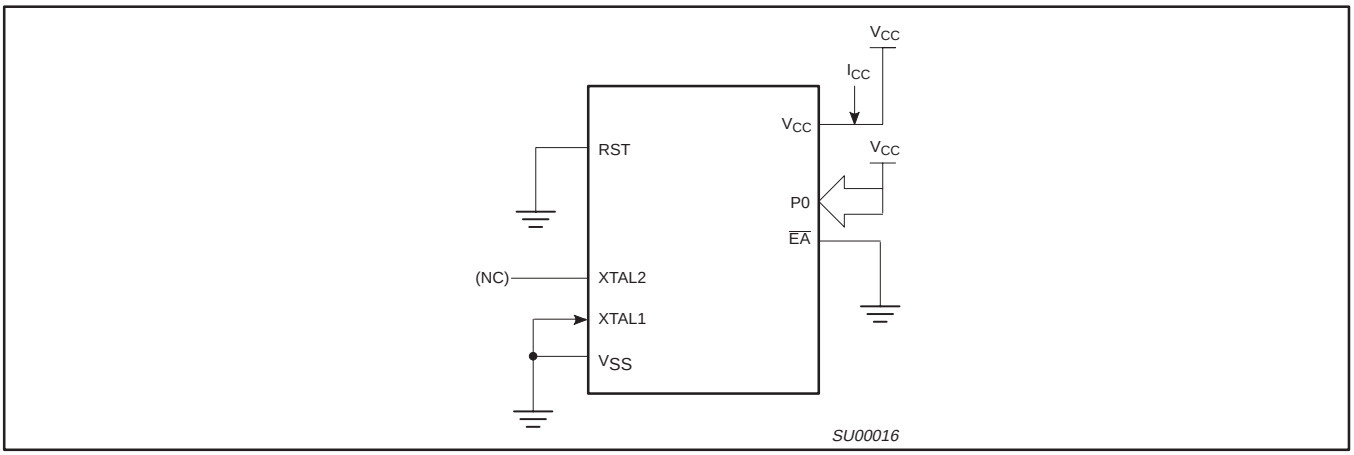


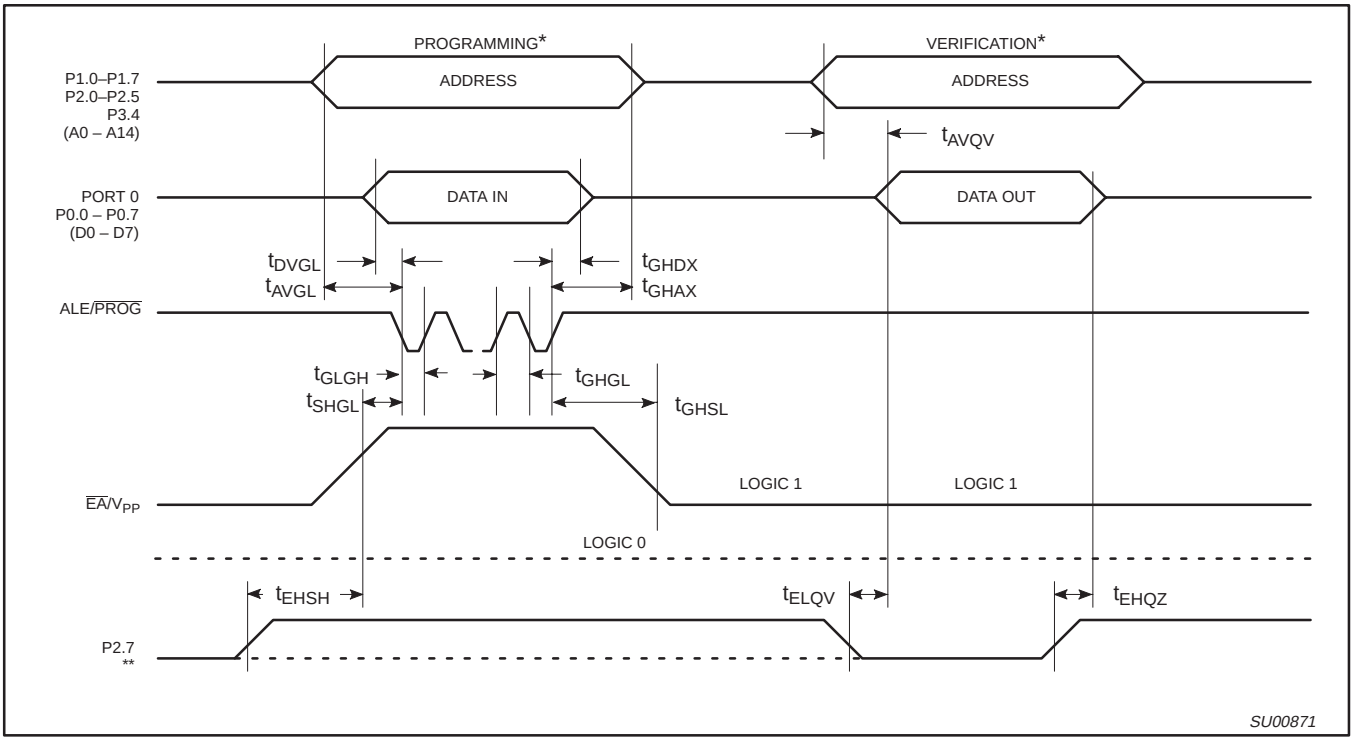
Figure 40. I_{CC} Test Condition, Power Down Mode
All other pins are disconnected. V_{CC} = 2V to 5.5V

EPROM PROGRAMMING AND VERIFICATION CHARACTERISTICS

T_{amb} = 21°C to +27°C, V_{CC} = 5V±10%, V_{SS} = 0V (See Figure 44)

SYMBOL	PARAMETER	MIN	MAX	UNIT
V_{PP}	Programming supply voltage	12.5	13.0	V
I_{PP}	Programming supply current		50 [1]	mA
$1/t_{CLCL}$	Oscillator frequency	4	6	MHz
t_{AVGL}	Address setup to $\overline{PROG}$ low	$48t_{CLCL}$		
t_{GHAX}	Address hold after $\overline{PROG}$	$48t_{CLCL}$		
t_{DVGL}	Data setup to $\overline{PROG}$ low	$48t_{CLCL}$		
t_{GHDX}	Data hold after $\overline{PROG}$	$48t_{CLCL}$		
t_{EHSH}	P2.7 ($\overline{ENABLE}$) high to V_{PP}	$48t_{CLCL}$		
t_{SHGL}	V_{PP} setup to $\overline{PROG}$ low	10		µs
t_{GHSL}	V_{PP} hold after $\overline{PROG}$	10		µs
t_{GLGH}	$\overline{PROG}$ width	90	110	µs
t_{AVQV}	Address to data valid		$48t_{CLCL}$	
t_{ELQZ}	$\overline{ENABLE}$ low to data valid		$48t_{CLCL}$	
t_{EHQZ}	Data float after $\overline{ENABLE}$	0	$48t_{CLCL}$	
t_{GHGL}	$\overline{PROG}$ high to $\overline{PROG}$ low	10		µs

NOTE:
1. Not tested.



NOTES:
* FOR PROGRAMMING CONFIGURATION SEE FIGURE 41.
FOR VERIFICATION CONDITIONS SEE FIGURE 43.
** SEE TABLE 9.

Figure 44. EPROM Programming and Verification

ROM CODE SUBMISSION FOR 16K ROM DEVICES (80C54, 83C51FB AND 83C51RB+)

When submitting ROM code for the 16K ROM devices, the following must be specified:

1. 16k byte user ROM data
2. 64 byte ROM encryption key
3. ROM security bits.

ADDRESS	CONTENT	BIT(S)	COMMENT
0000H to 3FFFH	DATA	7:0	User ROM Data
4000H to 403FH	KEY	7:0	ROM Encryption Key FFH = no encryption
4040H	SEC	0	ROM Security Bit 1 0 = enable security 1 = disable security
4040H	SEC	1	ROM Security Bit 2 0 = enable security 1 = disable security

Security Bit 1: When programmed, this bit has two effects on masked ROM parts:

1. External MOVC is disabled, and
2. $\overline{EA}$ is latched on Reset.

Security Bit 2: When programmed, this bit inhibits Verify User ROM.

NOTE: Security Bit 2 cannot be enabled unless Security Bit 1 is enabled.

If the ROM Code file does not include the options, the following information must be included with the ROM code.

For each of the following, check the appropriate box, and send to Philips along with the code:

Security Bit #1: ☐ Enabled ☐ Disabled

Security Bit #2: ☐ Enabled ☐ Disabled

Encryption: ☐ No ☐ Yes If Yes, must send key file.

ROM CODE SUBMISSION FOR 64K ROM DEVICE (83C51RD+)

When submitting ROM code for the 64K ROM devices, the following must be specified:

1. 64k byte user ROM data
2. 64 byte ROM encryption key
3. ROM security bits.

ADDRESS	CONTENT	BIT(S)	COMMENT
0000H to FFFFH	DATA	7:0	User ROM Data
10000H to 1003FH	KEY	7:0	ROM Encryption Key FFH = no encryption
10040H	SEC	0	ROM Security Bit 1 0 = enable security 1 = disable security
10040H	SEC	1	ROM Security Bit 2 0 = enable security 1 = disable security

Security Bit 1: When programmed, this bit has two effects on masked ROM parts:

1. External MOVC is disabled, and
2. $\overline{EA}$ is latched on Reset.

Security Bit 2: When programmed, this bit inhibits Verify User ROM.

NOTE: Security Bit 2 cannot be enabled unless Security Bit 1 is enabled.

If the ROM Code file does not include the options, the following information must be included with the ROM code.

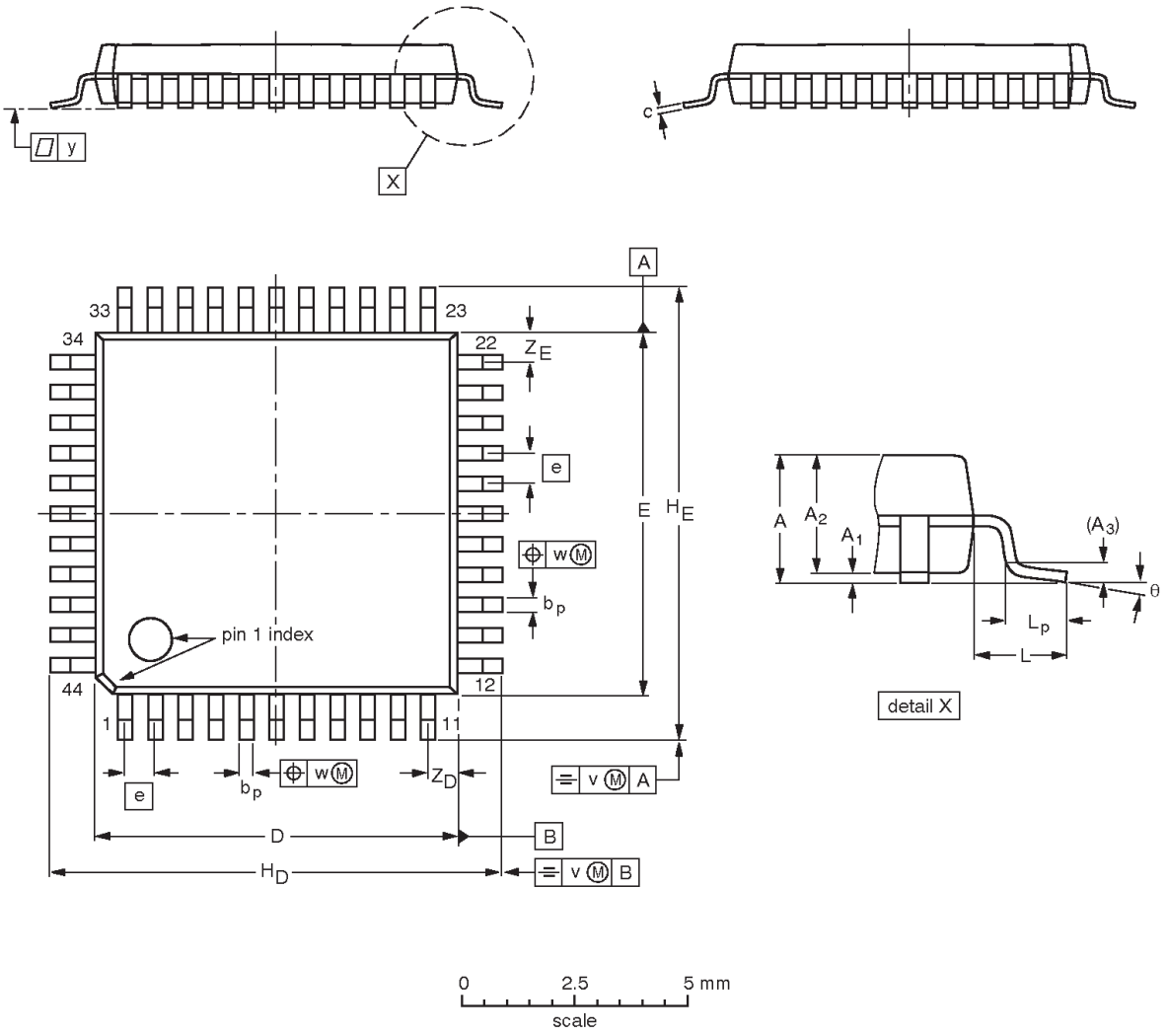
For each of the following, check the appropriate box, and send to Philips along with the code:

Security Bit #1: ☐ Enabled ☐ Disabled

Security Bit #2: ☐ Enabled ☐ Disabled

Encryption: ☐ No ☐ Yes If Yes, must send

QFP44: plastic quad flat package; 44 leads (lead length 1.3 mm); body 10 x 10 x 1.75 mm SOT307-2



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A_1	A_2	A_3	b_p	c	$D^{(1)}$	$E^{(1)}$	e	H_D	H_E	L	L_p	v	w	y	$Z_D^{(1)}$	$Z_E^{(1)}$	θ
mm	2.10	0.25 0.05	1.85 1.65	0.25	0.40 0.20	0.25 0.14	10.1 9.9	10.1 9.9	0.8	12.9 12.3	12.9 12.3	1.3	0.95 0.55	0.15	0.15	0.1	1.2 0.8	1.2 0.8	10^o 0^o

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT307-2						~~95-02-04~~ 97-08-01